



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

USAMI, Tatsuya

Serial No.: 09/627,418

Filed: July 27, 2000

For: SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THE SAME

Honorable Assistant Commissioner of Patents
Washington, D.C. 20231

Box AF

Group Art Unit: 2814

Examiner: Quach, T.

AF/2814
#11B Amt
J/e M. Brunson
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AMENDMENT UNDER 37 C.F.R. §1.116

Sir:

In response to the Office Action dated June 3, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claim 3 without prejudice or disclaimer.
Please revise claims 1 and 4 to read as follows.

1. (Amended) A semiconductor device comprising:

a plurality of wiring lines which are formed of Cu whose concentration is equal to or higher than 10^{19} atoms/cm³;

an insulating layer which has a property that Cu is unlikely to enter said insulating layer and which insulates between said plurality of wiring lines; and

at least one adhesion layer formed in an interface between said plurality of wiring lines and said insulating layer, said at least one adhesion layer allowing said plurality of wiring lines and said insulating layer to adhere to one another.